

REMARKS

In response to the April 2, 2009 Final Office Action and the June 10, 2009 Advisory Action, each independent claim is amended herein. Particularly, independent claims 1, 14, 23 and 24 each now recite that the module housing is a plastic injection-molded housing and each recess in the module housing is arranged between adjacent substrate regions. Each newly amended independent claim further recites that the thickness of the power semiconductor module is reduced between adjacent substrate regions due to the recesses. No new matter is added by way of these claim amendments. For example, the Examiner is kindly directed to Figure 1 and the corresponding text of the instant application.

The Ali reference (U.S. Patent No. 6,157,538) fails to teach or suggest any of the newly added independent claim features. Particularly, Ali does not disclose a plastic injection-molded housing. Instead, Ali's housing 11 includes a printed circuit board support structure 12 and a door 50. Ali also does not disclose a recess arranged between adjacent substrate regions. Ali further fails to disclose a power semiconductor module having a thickness which is reduced between adjacent substrate regions due to recesses in a plastic injection-molded housing. In complete contrast, Ali's system 10 has a uniform thickness.

Conclusion

In view of the amendments and remarks made herein, Applicant respectfully submits that the present application is in condition for immediate allowance. Action to such effect is respectfully requested. The Examiner is encouraged to contact Applicant's attorney at (919)-854-1844 if any outstanding matters can be readily addressed by a phone call.

Respectfully submitted,

COATS & BENNETT, P.L.L.C.



Mark R. Bilak
Registration No.: 47,423

1400 Crescent Green, Suite 300
Cary, NC 27518

Telephone: (919) 854-1844
Facsimile: (919) 854-2084

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